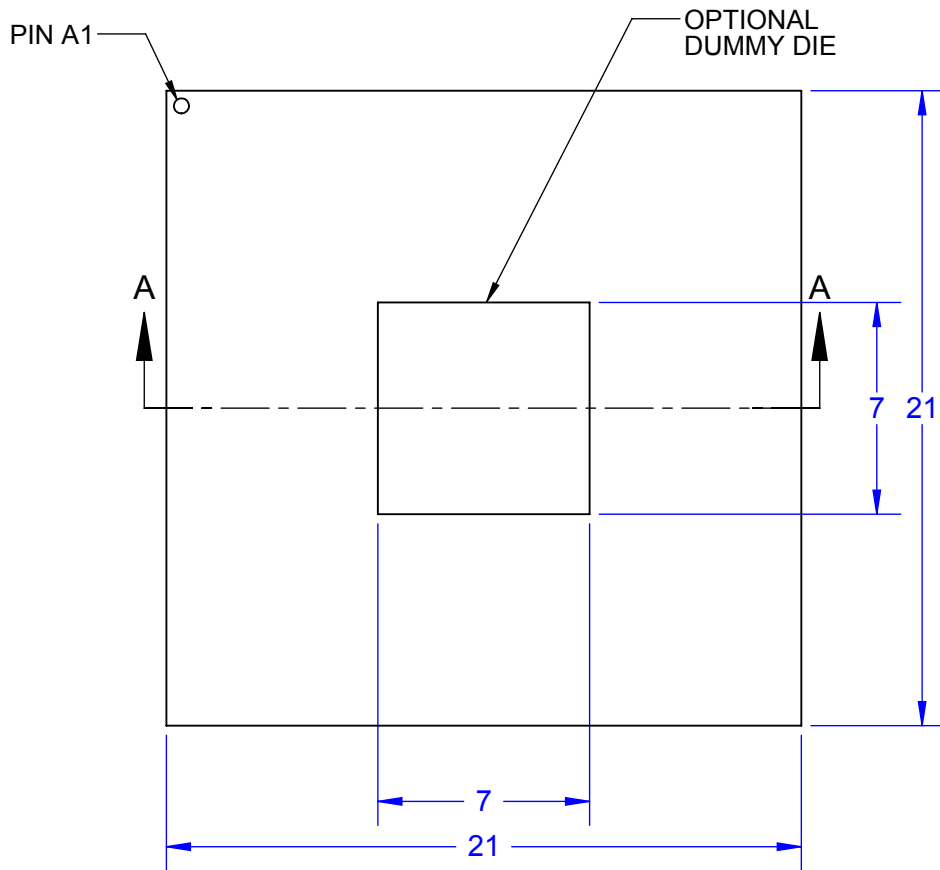
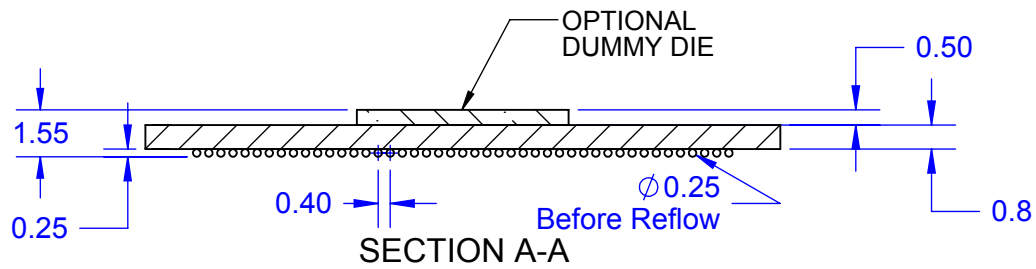
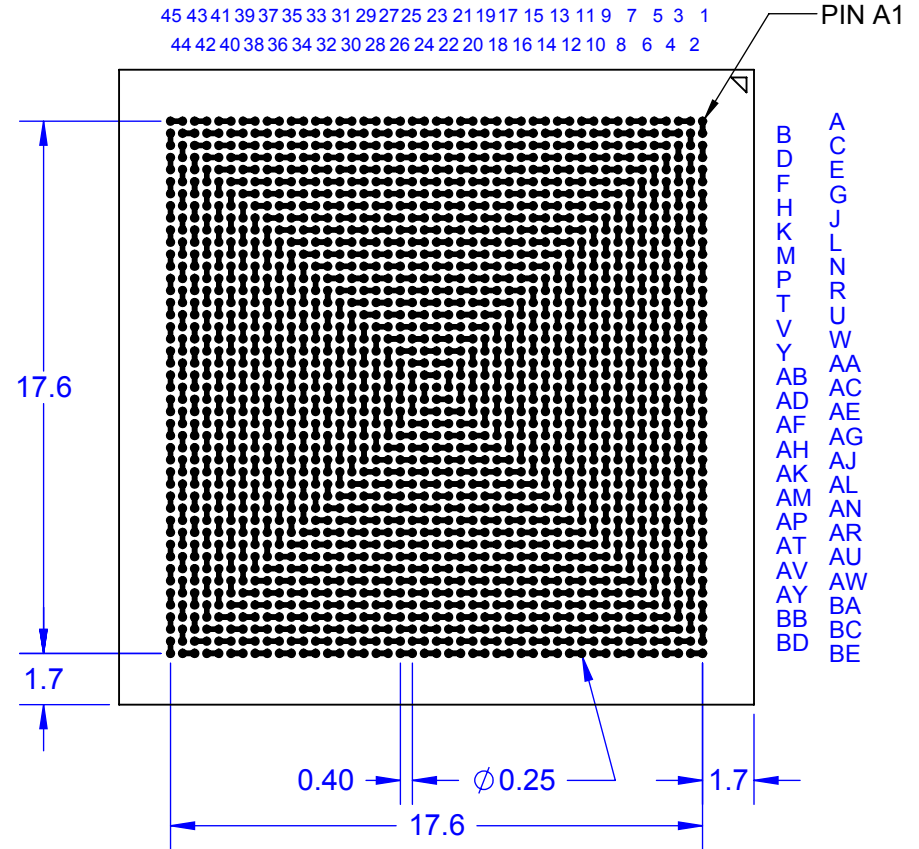


TOP VIEW



BALL VIEW



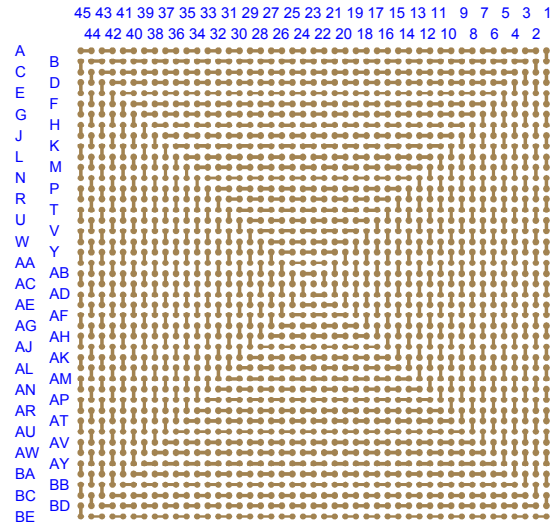
Notes: (Unless Otherwise Specified).

- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.25mm (9.8 MIL).
- 4) SOLDER MASK DEFINED PAD OPENING: 0.22mm (8.7 MIL).
- 5) PAD Cu DIAMETER: 0.305mm (12 MIL).
- 6) SUBSTRATE MATERIAL: BT (ALTERNATE FR4).
- 7) DUMMY DIE IS OPTIONAL.
- 8) DAISY CHAIN PATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMENDED BAKING 24 HOURS @ 125°C TO REMOVE MOISTURE PRIOR SOLDERING TO PC BOARD.

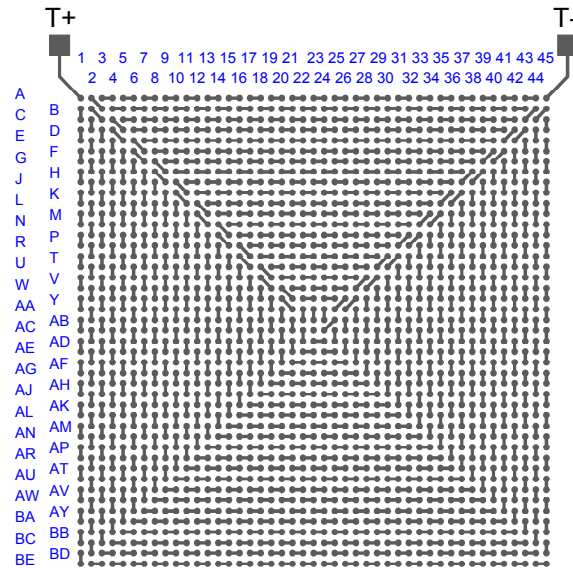
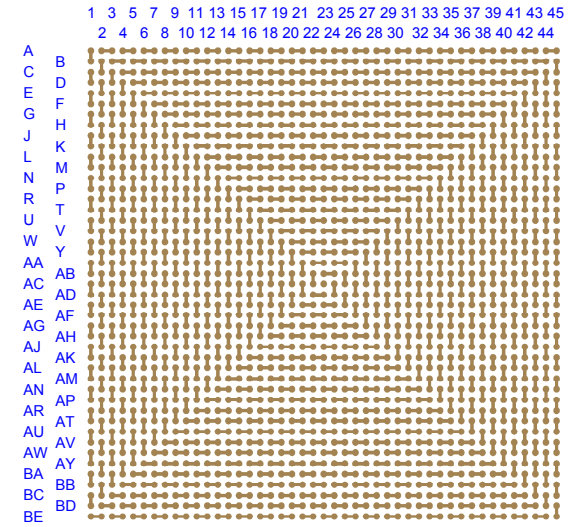
PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	Pb-Free	RoHS	Si DIE
BGA2025T.4C-DC459D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
BGA2025T.4-DC459D	Sn63/Pb37	NO	NO	YES

APPROVALS	DATE	TopLine®		
DRAWN T.Au	09/19/13			
ENG M. Hart	09/19/13	TITLE		LPGA2025T.4-DC459D DAISY CHAIN DUMMY
MFG		SCALE	SIZE	DRAWING NO.
QA		4:1	A	544591
CUST				REV A
REVISED		DO NOT SCALE DRAWING		SHEET 1 OF 2

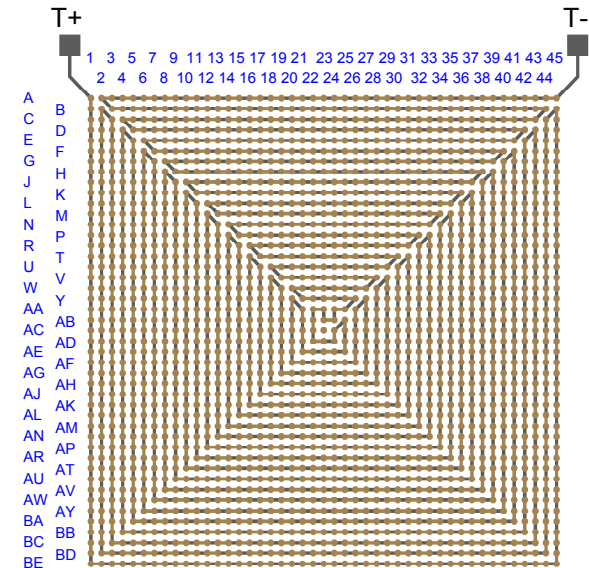
BALL VIEW



BOTTOM SIDE (TOP X-RAY VIEW)



TEST VEHICLE BOARD



AFTER MOUNTING

Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.305mm (12 MIL).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.127mm (5 MIL).
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING: 0.22mm (8.7 MIL).

TopLine®			
TITLE		LBGA2025T.4-DC459D DAISY CHAIN DUMMY	
SCALE	SIZE	DRAWING NO.	REV
3.5:1	A	544591	A
DO NOT SCALE DRAWING			SHEET 2 OF 2